



DESCRIPTION

The S1A~S1M are available in SMA package

ORDERING INFORMATION

Package Type	Part Number
SMA	S1A
	S1B
	S1D
	S1G
	S1J
	S1K
	S1M
Note	SPQ: 5,000pcs/Reel

AiT provides all RoHS Compliant Products

PIN DESCRIPTION



FEATURES

- For surface mounted applications
- Low profile package
- Glass Passivated Chip Junction
- Easy to pick and place
- Available in SMA package

MECHANICAL DATA

Case: SMA

Terminals: Solderable per MIL-STD-750,
Method 2026

Approx. Weight: 0.055g / 0.002oz



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified.

Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.

Parameter	Symbol	S1A	S1B	S1D	S1G	S1J	S1K	S1M	Unit
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current	$I_{F(AV)}$	1							A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load	I_{FSM}	35							A
Maximum Instantaneous Forward Voltage at 1.0A	V_F	1.1							V
Maximum DC Reverse Current @ $T_A=25^\circ\text{C}$ at Rated DC Blocking Voltage @ $T_A=125^\circ\text{C}$	I_R	5 50							μA
Typical junction capacitance ^{NOTE1}	C_J	15							pF
Typical thermal resistance ^{NOTE2}	$R_{\theta JA}$	75							$^\circ\text{C/W}$
Operating and Storage Temperature Range	$T_J,$ T_{STG}	-55 to 150							$^\circ\text{C}$

NOTE1: Measured at 1 MHz and applied reverse voltage of 4 V D.C

NOTE2: P.C.B. mounted with 2.0" X 2.0" (5 X 5 cm) copper pad areas.



TYPICAL CHARACTERISTICS

Figure 1. Forward Current Derating Curve

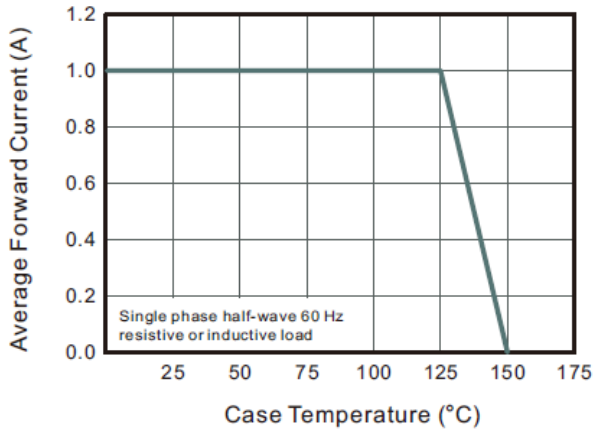


Figure 2. Typical Reverse Characteristics

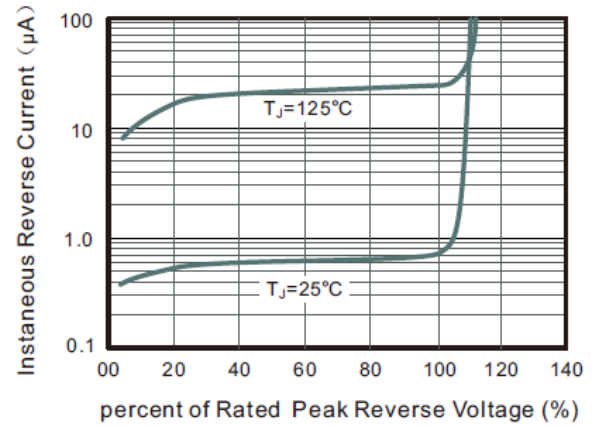


Figure 3. Typical Forward Characteristic

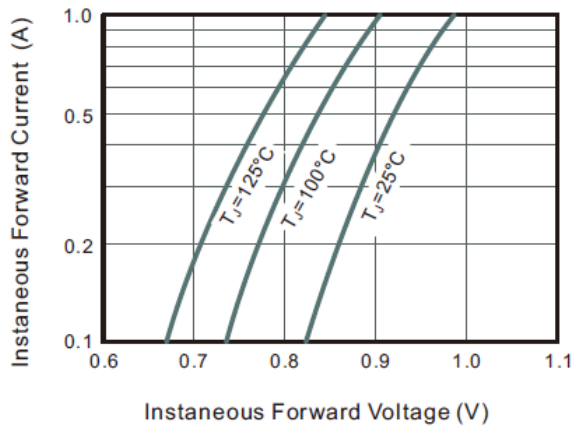


Figure 4. Typical Junction Capacitance

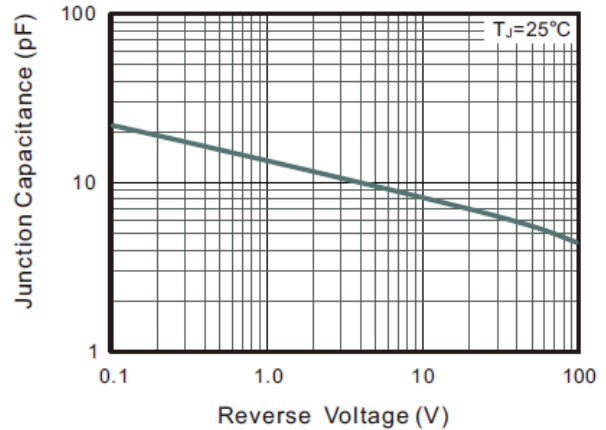
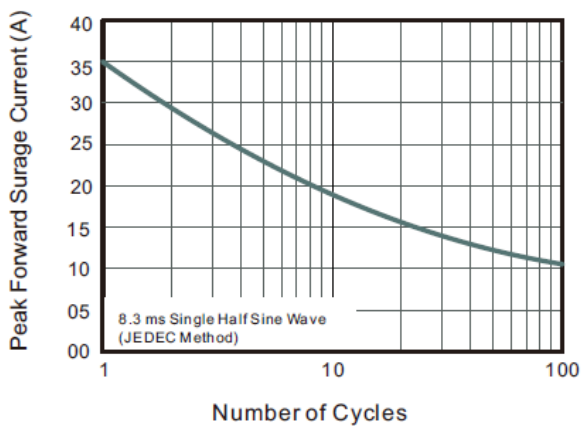


Figure 5. Maximum Non-Repetitive Peak Forward Surge Current

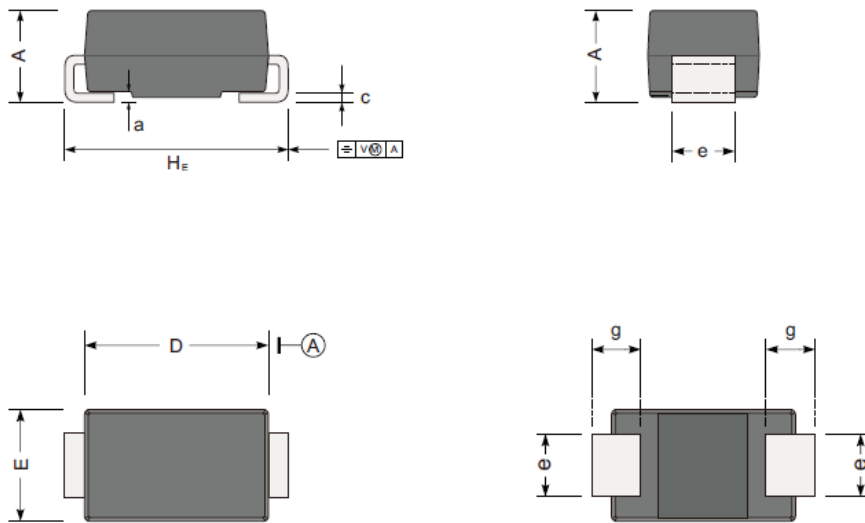




PACKAGE INFORMATION

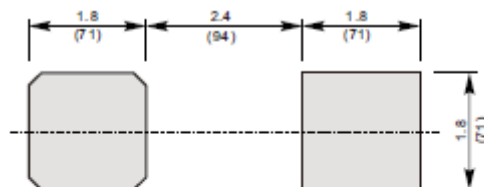
Dimension in SMA Package (Unit: mm/mil)

Plastic surface mounted package; 2 leads



UNIT		A	D	E	H _E	c	e	g	a
mm	max	2.2	4.5	2.7	5.2	0.31	1.6	1.5	0.3
	min	1.9	4.0	2.3	4.7	0.15	1.3	0.9	
mil	max	87	181	106	205	12	63	59	12
	min	75	157	91	185	6	51	35	

The recommended mounting pad size



Unit: $\frac{\text{mm}}{\text{mil}}$



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